



BERGQUIST GAP PAD[®] TGP 12000ULM

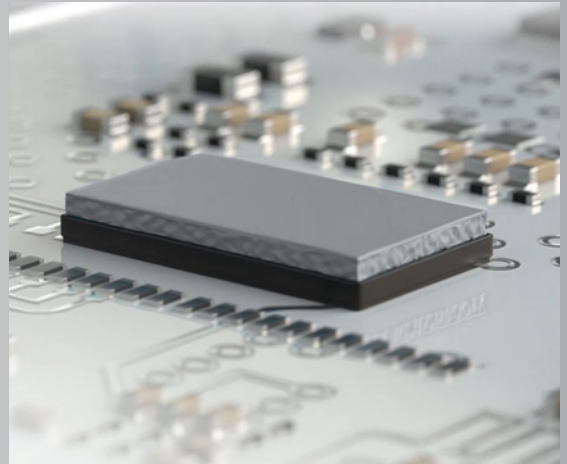
HIGH THERMAL CONDUCTIVITY, ULTRA-LOW MODULUS GAP PAD[®]

Formulated to address the demands of high power density designs found in hyperscale and cloud scale datacenters, *BERGQUIST GAP PAD[®] TGP 12000ULM* is a high thermal conductivity, ultra-low modulus thermal interface material (TIM) well-suited for modern datacom applications. Among the highest performing TIMs available on the market, *BERGQUIST GAP PAD TGP 12000ULM* combines very high thermal conductivity of 12.0 W/m-K with soft, conforming properties to ensure excellent wet out at the interface for optimized thermal transfer and low assembly stress. *BERGQUIST GAP PAD TGP 12000ULM* is built on a silicone-based resin platform with unique filler technology to accommodate excellent heat dissipation while simultaneously reducing stress on small footprint, miniaturized components.



Key Benefits

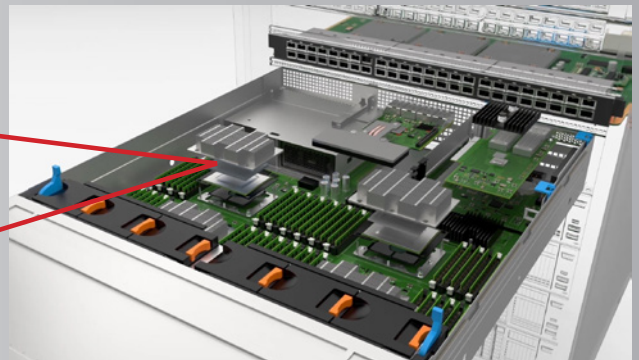
- Low assembly stress due to ultra-low modulus of 75 hardness (Shore 000, ASTM D2240) and 173 Young's Modulus (kPa, ASTM D575)
- Excellent conformability to rough or irregular surfaces
- Thorough wet out at the interface for maximized thermal transfer
- High thermal conductivity of 12.0 W/m-K (ASTM D5470)
- Simplified application and processability; supplied in pre-cut, custom-sized pads with high tack on both sides
- Ability to use a single pad for multi-height chips and/or multiple devices
- Room temperature storage



PRODUCT PROPERTIES	BERGQUIST GAP PAD® TGP 12000ULM
Hardness (Shore 000)	68
Inherent Surface Tack	2
Thermal Conductivity (W/m-K)	12
Young's Modulus (kPa)	103
Dielectric Breakdown Voltage: 0.04 inch sample (VAC)	6,200
Appearance	Gray

Typical applications

- Telecommunications (routers, switches and base stations)
- Optical Transceivers
- ASICs and DSPs



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